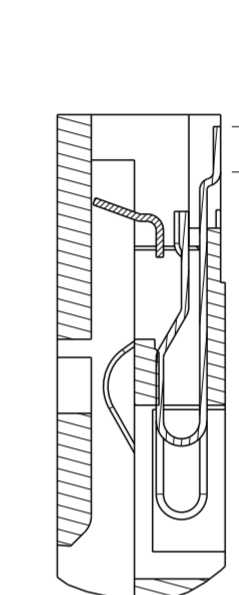
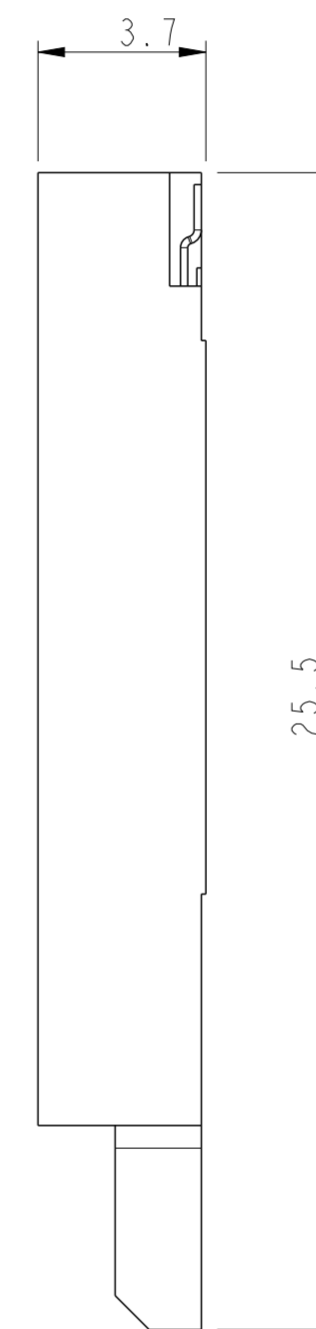
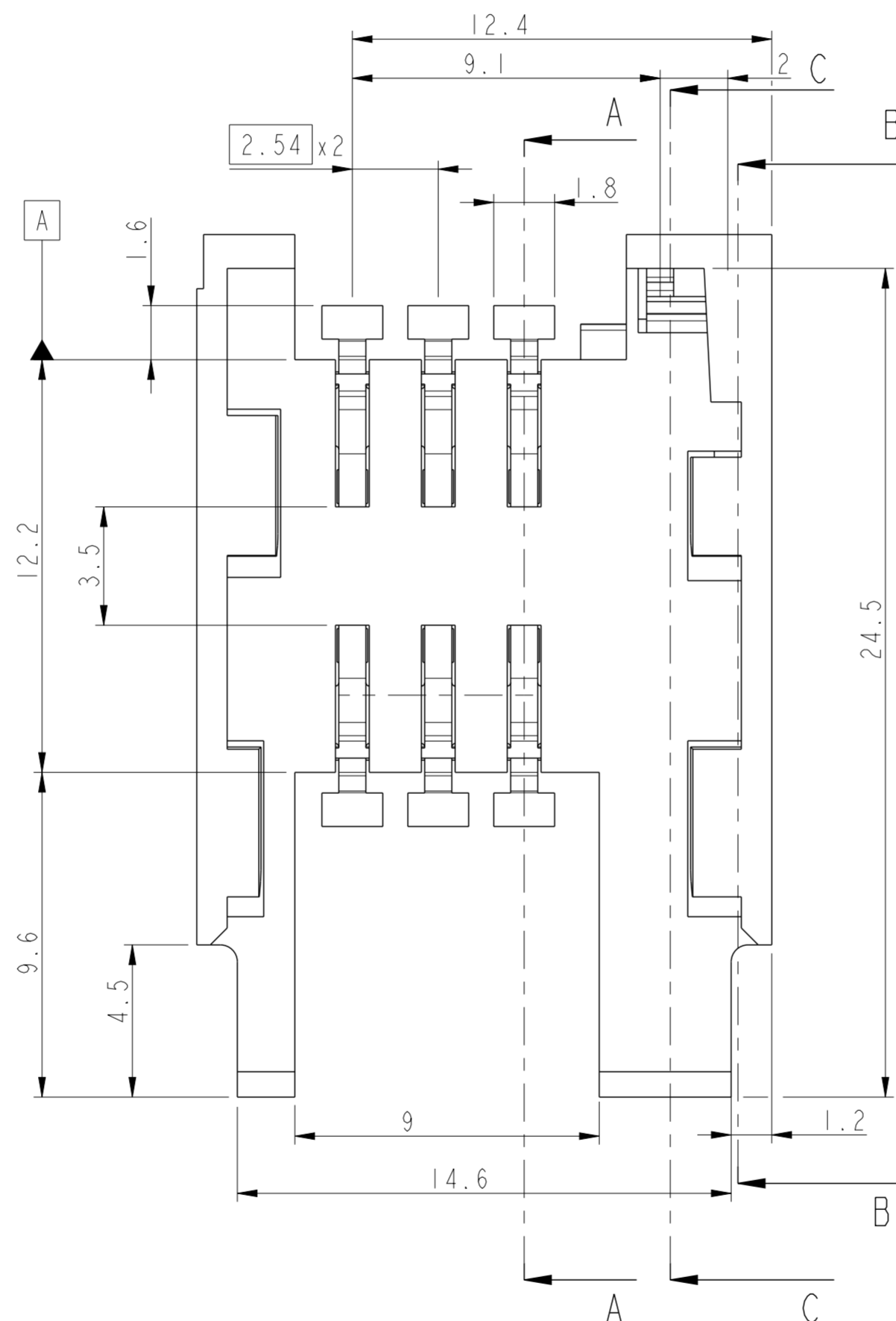
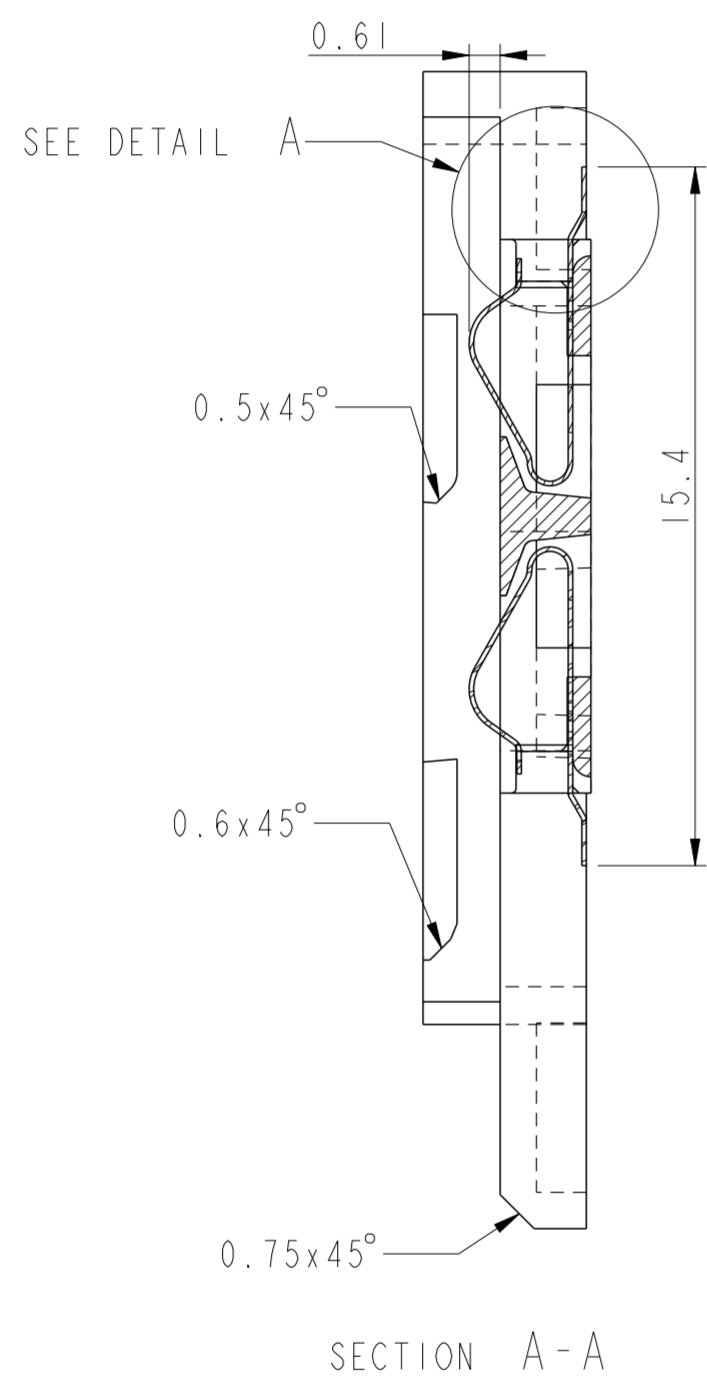
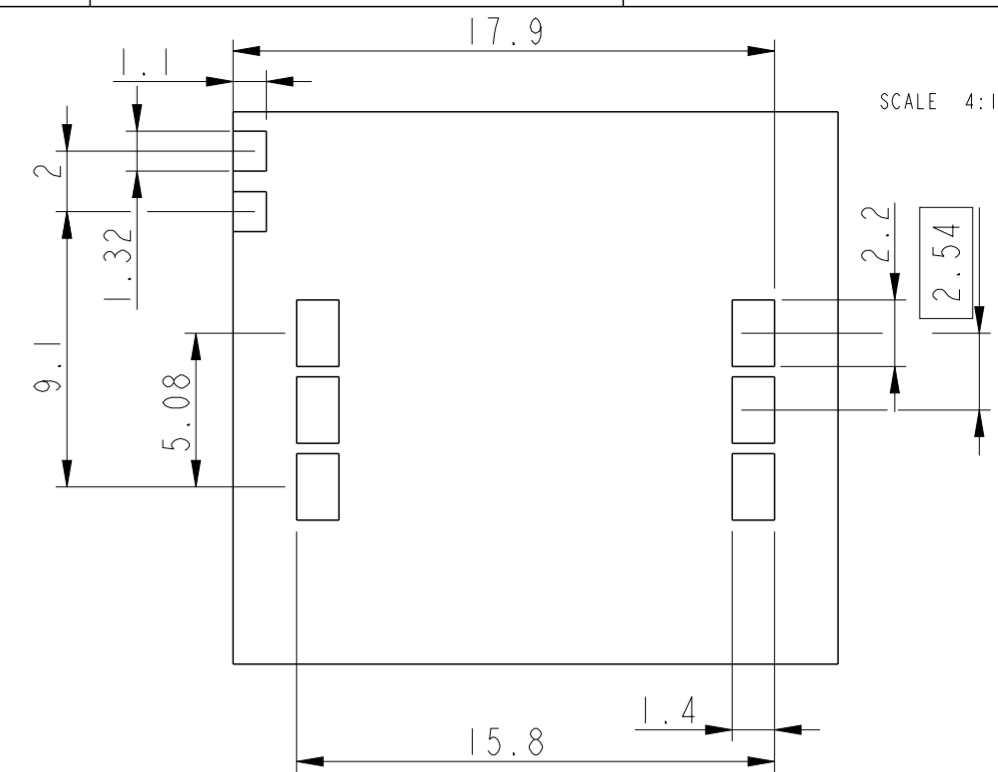
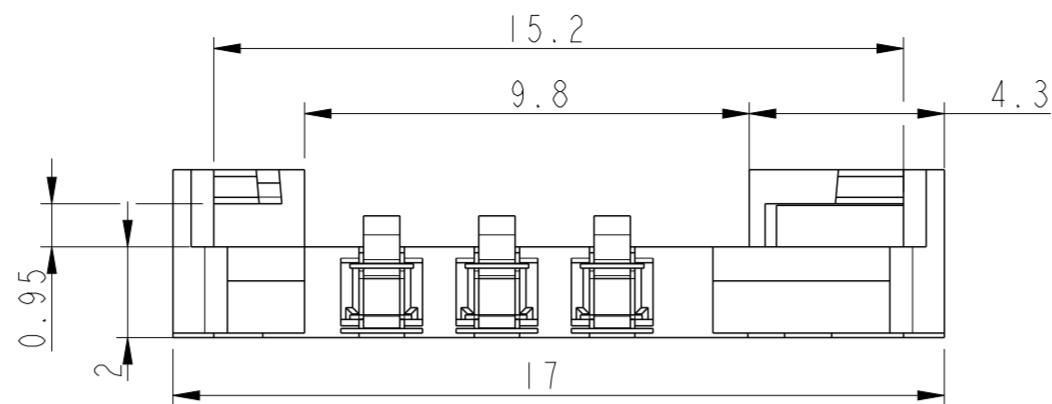
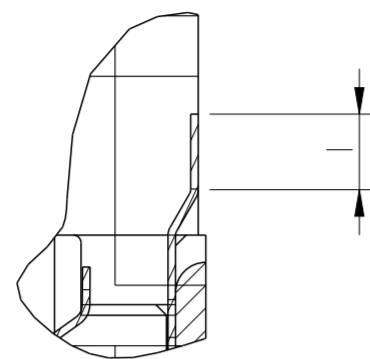
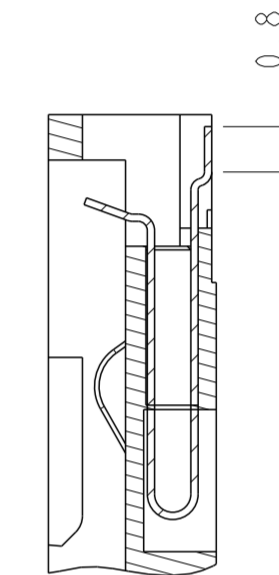


PART NUMBER
LEAD FREE VERSION
7111SI1615A02LF

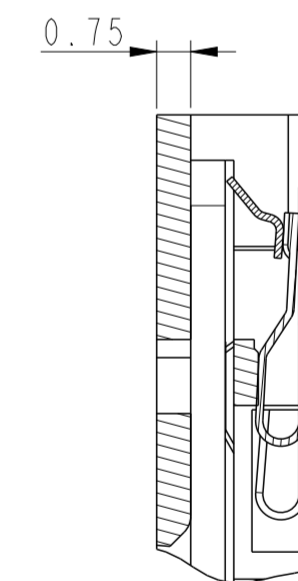
DETAIL A
SCALE 10:1



SECTION B-B



SECTION C-C



CARD
SECTION B-B
SCALE 6:1

DETAIL OF SWITCH

LEAD FREE VERSION:

"This product meets European Union Directives and other country regulations as described in GS-22-008"

The housing will withstand exposure to 260°C peak temperature for 10 seconds in a convection reflow oven.

PROCESSING

Ni 2 μm
Gold 2.5 μm/Equivalent PdNi over Ni on contact area
Solder tail: Matte tin 2.5 μm (for lead free version)

GENERAL TOLERANCES: ±0.1

www.fciconnect.com		surface	tolerance std	projection	mm
		ISO 1302	ISO 406 ISO 1101		
TOLERANCES UNLESS OTHERWISE SPECIFIED					
Dr	BERNARDET	1998/09/02	ANGULAR	0.x	±
Eng	ODIC	1998/09/02	LINEAR	0.xx	±
Chr	DILIPTHOMAS	2006/07/18	0° ±°	0.xxx	±
Appr	K.V.SIVADAS	2006/07/18	Product family		MOBILE IO
				size	A2
				Scale	6:1
				ECN	109-0291
				Spec ref	--
FCJ		SIMCARD CONNECTOR WITH SWITCH		Rev.	
TYPE SI6		VJW_54479		F	
catalog no		SEE NOTES		CUSTOMER	
		sheet 1 of 1			

rev	ecn no	dr	date
01	-	JBB	1998-09-02
A	-	-	2001-12-06
B	-	MPE	2002-03-06
C	LS2025	MPE	2002-05-04
D	I05-0167	NT	2005/09/23
E	I06-0121	DTK	2006/07/18
F	I09-0291	RPK	2009/12/30